

Dynasolve™ CU-7



Cured Polyimide Cleaning Solvent



Dynasolve CU-7 is a formulated solvent used to remove cured polyimide materials. It is used in both industrial and electronic applications. It is used extensively in the fiber optics industry.

CLEANING APPLICATIONS:

Removing polyimide materials used in electronic / fiber optics applications

Industrial polyimide removal and cleaning

ADVANTAGES:

More efficient than acetone, MEK & other solvents

No chlorinated, acidic or caustic components

High resin loading capacity allows for reuse and reduced cost of ownership

Formulated to be highly selective

High flash point

SPECIFICATIONS:

Specific gravity: 1.03

Boiling point: 401°F (205°C)

Flash point: 198°F (92°C)

MATERIALS REMOVED:

Cured polyimide materials

PRODUCT USAGE GUIDELINES

(SEE SDS FOR EH&S INFORMATION)

1. Heat Dynasolve CU-7 to 180°F (82°C) and immerse part.
2. Observe carefully. If polyimide material appears unaffected after 1 hour, increase temperature to 250° – 350°F (121° – 176°C).
3. After successful removal of polyimide material, rinse with alcohol or water.
4. If polyimide material is unaffected by Dynasolve CU-7 after 2 hours, call for technical support.

MATERIAL COMPATIBILITY:

Recommended materials including:

All metals

Teflon®

Polyethylene & polypropylene

Avoid materials including:

Viton®

PVC

Urethane



For more information, please contact us at:

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